

### REMARKS

Claims 1 – 34 are pending in the application. Claims 1-11 and 25 – 33 have been allowed.

The drawings have been objected to by the Draftsperson under 37 C.F.R. §1.84(p) as containing numbers and reference characters not plain and legible as well as having figure legends which are poor in FIGS. 1a-14b. In order to overcome this objection, corrected drawings of FIGS. 1a-14b are submitted herewith correcting the defects noted by the Draftsperson. Also submitted are corrected FIGS. 15-23 containing numbers and reference characters which are plain and legible. Approval of the drawings is respectfully requested.

Claims 12 – 14 and 34 have been rejected under 35 USC §103(a) as being unpatentable over WO 98/39501, hereinafter "WO '501." The Examiner states the cited reference discloses the basic claimed procedure for fabrication and packaging of at least one microstructured molded part as a magazine/molded part composite including the step of replicative fabricating at least one microstructured molded part using a prefabricated magazine. The Examiner states that the claimed second step of removing an entire composite of the magazine and molded parts simultaneously from a mold is well known and would have been obvious to one of ordinary skill in the art to prepare the mold for its next molding cycle.

Applicants respectfully submit the WO '501 reference cannot teach or suggest Applicants' invention as defined by the limitations of independent Claim 12. The WO '501 reference teaches the preparation of two different types of microcomponents. The first type of microcomponent is formed from an electrically non-conductive molding material, such as an epoxy resin. The second type of microcomponents are formed from an electrically conductive metallic material only utilizing galvanic methods, i.e., such as electrodeposition.

The WO '501 reference can only teach microcomponents of the second type (conductive metallic material) being formed using galvanic methods in conjunction with a prefabricated magazine. There is no teaching or suggestion within the WO '501 reference to utilize the same prefabricated magazine several times for the replicative fabrication of microcomponents as claimed in step "a" of independent

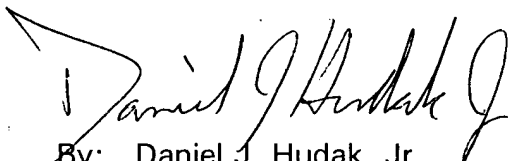
Claim 12 for production of the second type of microcomponents. There is especially no teaching or suggestion in the WO '501 reference for utilizing a prefabricated magazine to produce microcomponents of the first type, i.e., non-conductive molding material which is comparable to the microcomponents disclosed in the present application, much less a teaching for utilizing a prefabricated magazine for replicative fabricating.

Accordingly, the WO '501 reference can not teach or suggest Applicant's independent Claim 12 limitation of replicatively fabricating at least one microstructured molded part using a prefabricated magazine. Only hindsight motivation can be utilized to impermissibly modify the teaching of the prior art WO '501 reference to render the present invention obvious.

It is respectfully submitted that the claims are in condition for allowance and a notice of such is earnestly solicited. Should the Examiner have any questions or concerns, a telephone call to the undersigned would be greatly appreciated in order to expedite allowance of the application.

Respectfully submitted,

**HUDAK, SHUNK & FARINE CO. LPA**

A handwritten signature in dark ink, appearing to read "Daniel J. Hudak, Jr.", written in a cursive style.

By: Daniel J. Hudak, Jr.  
Registration No. 47,669

DJHjr/wj

2020 Front Street  
Suite 307  
Cuyahoga Falls, OH 44221  
(330) 535-2220  
Attorney Docket No.: FMW-QQ-PCT-US

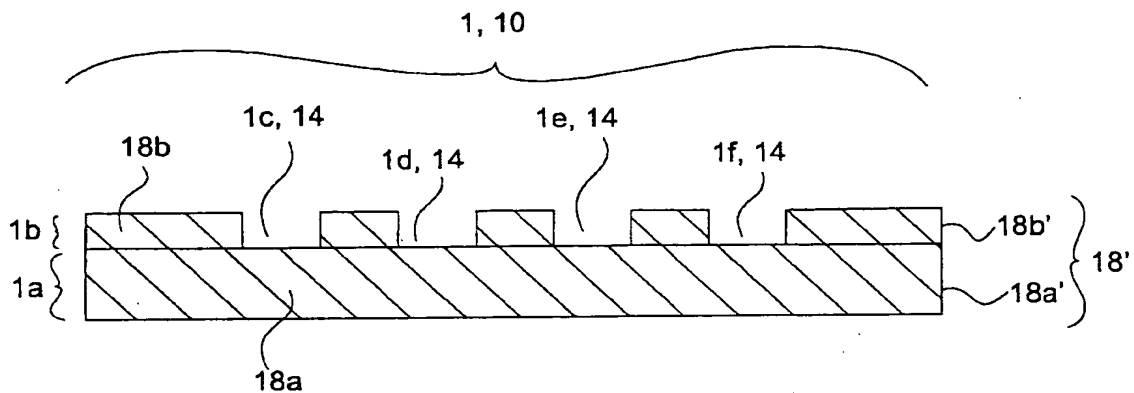


Fig. 1b

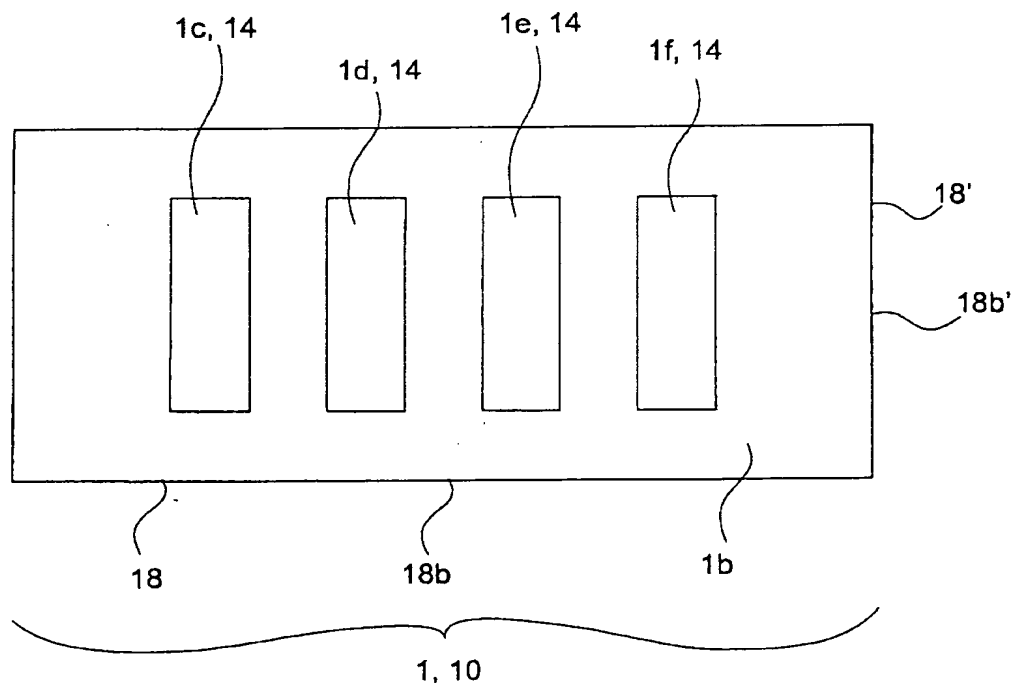
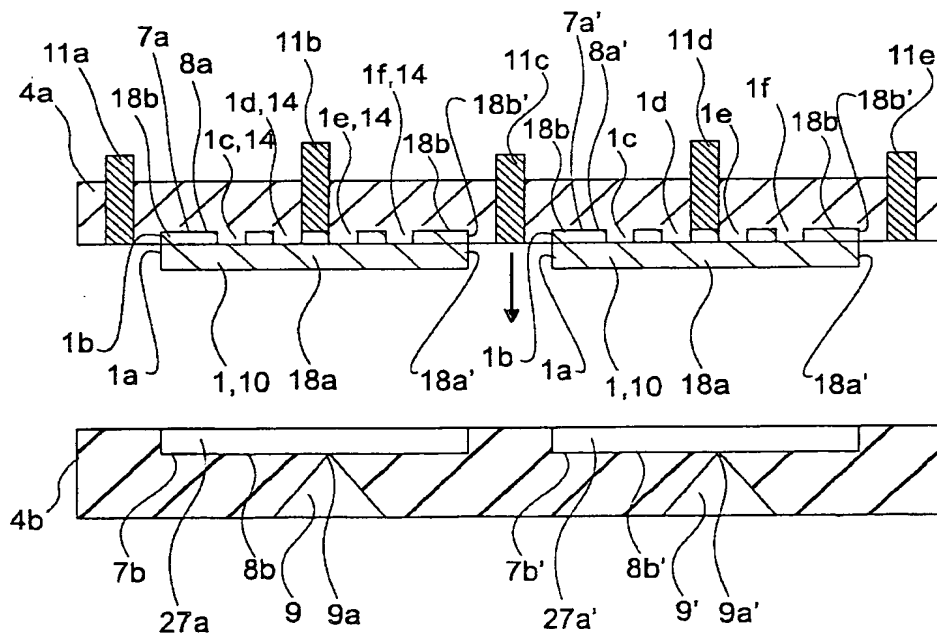
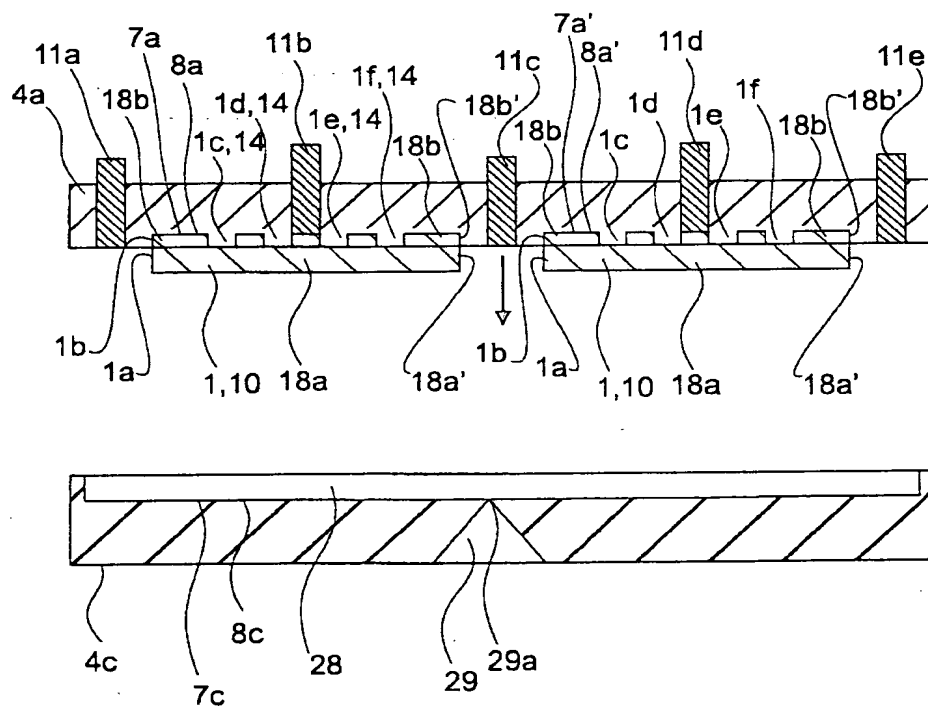
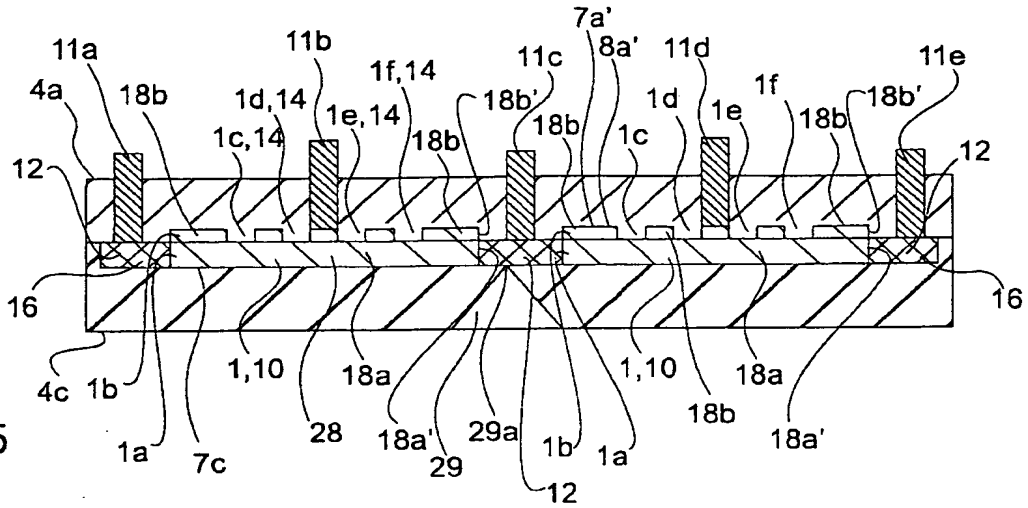


Fig. 1a







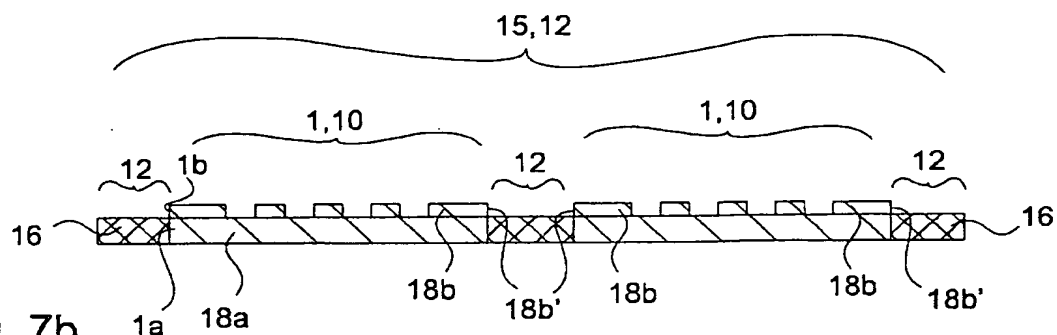


Fig. 7b

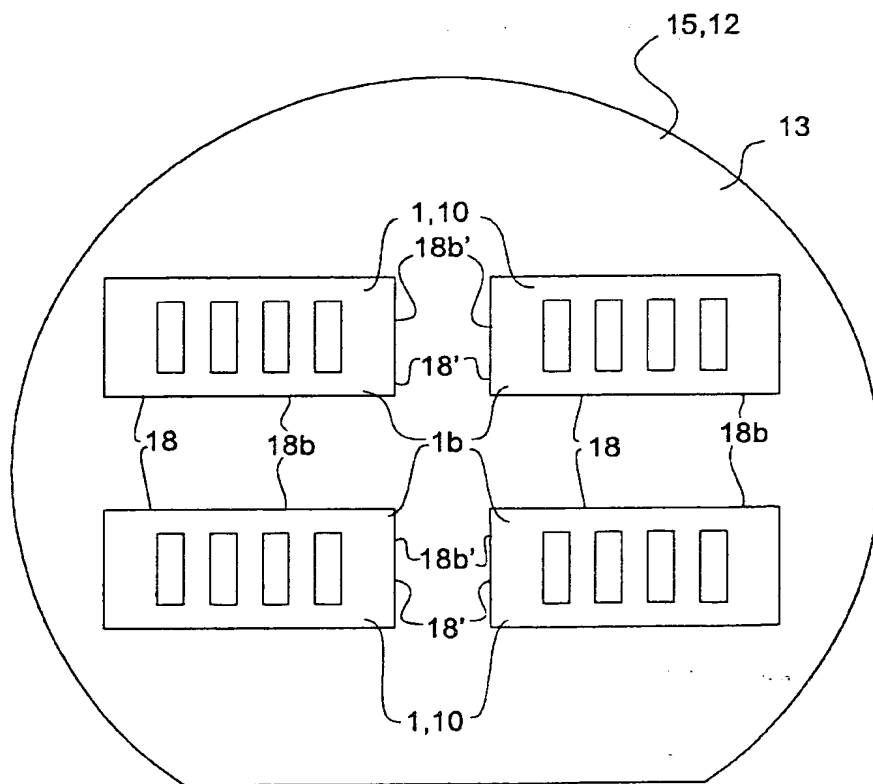


Fig. 7a

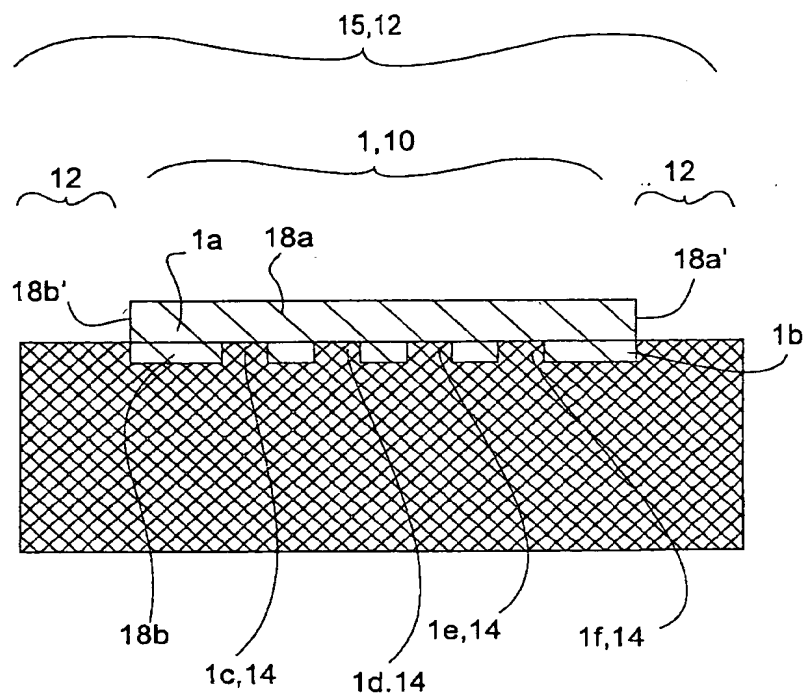


Fig. 8



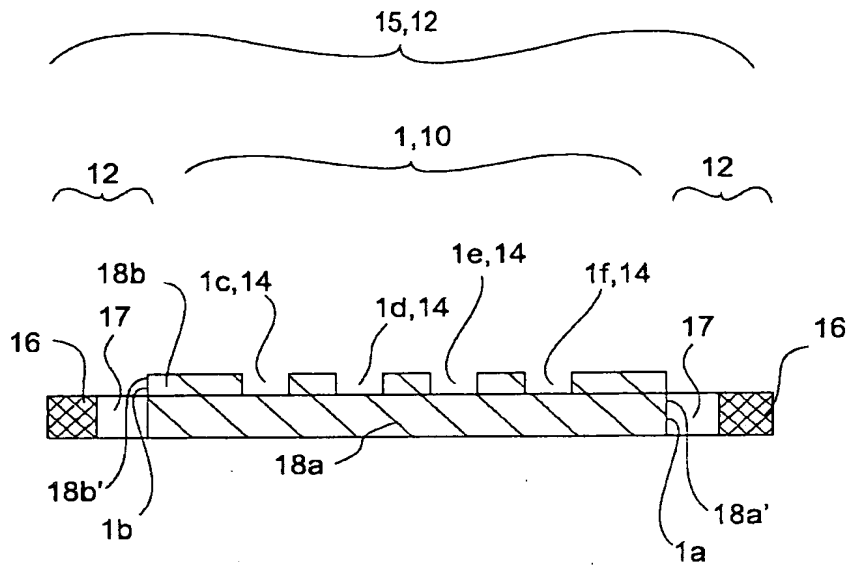


Fig. 9b

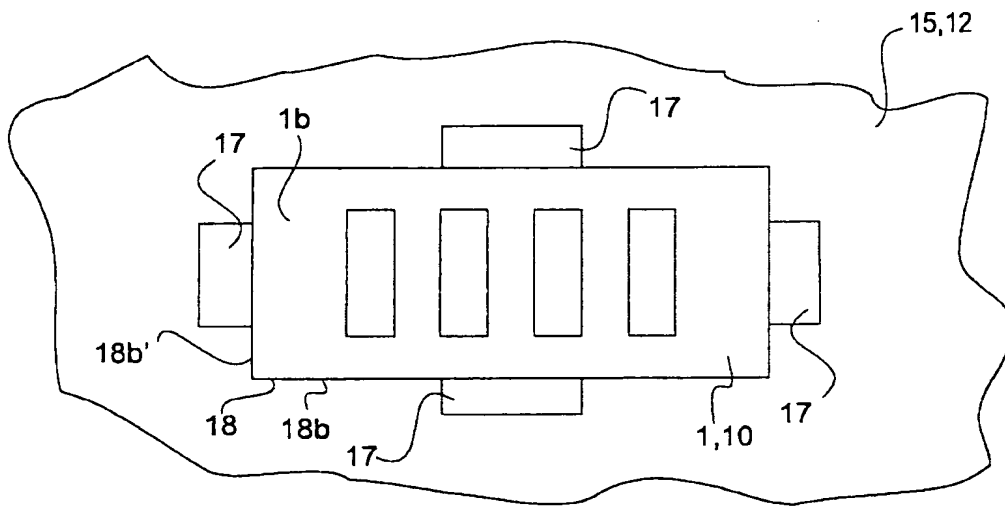


Fig. 9a

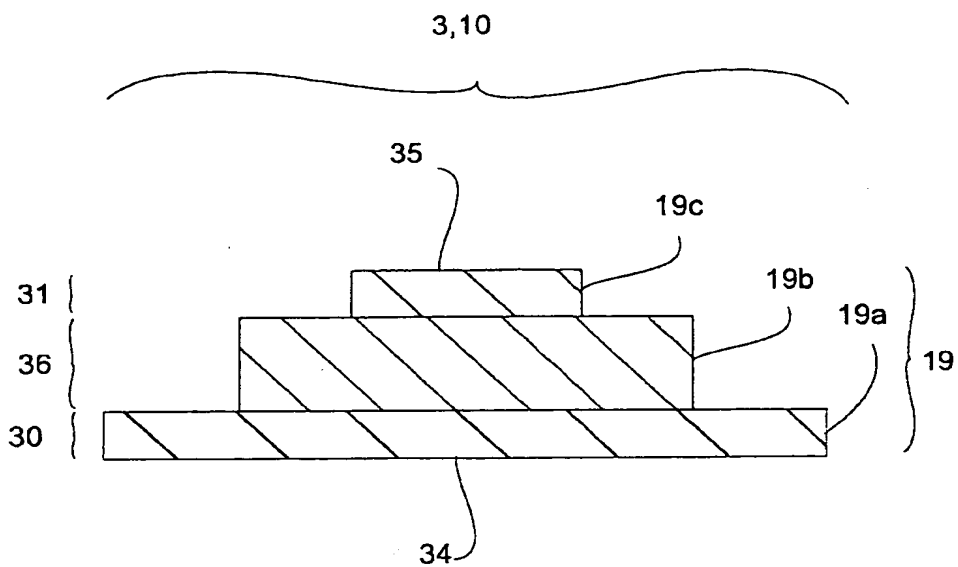


Fig. 10b

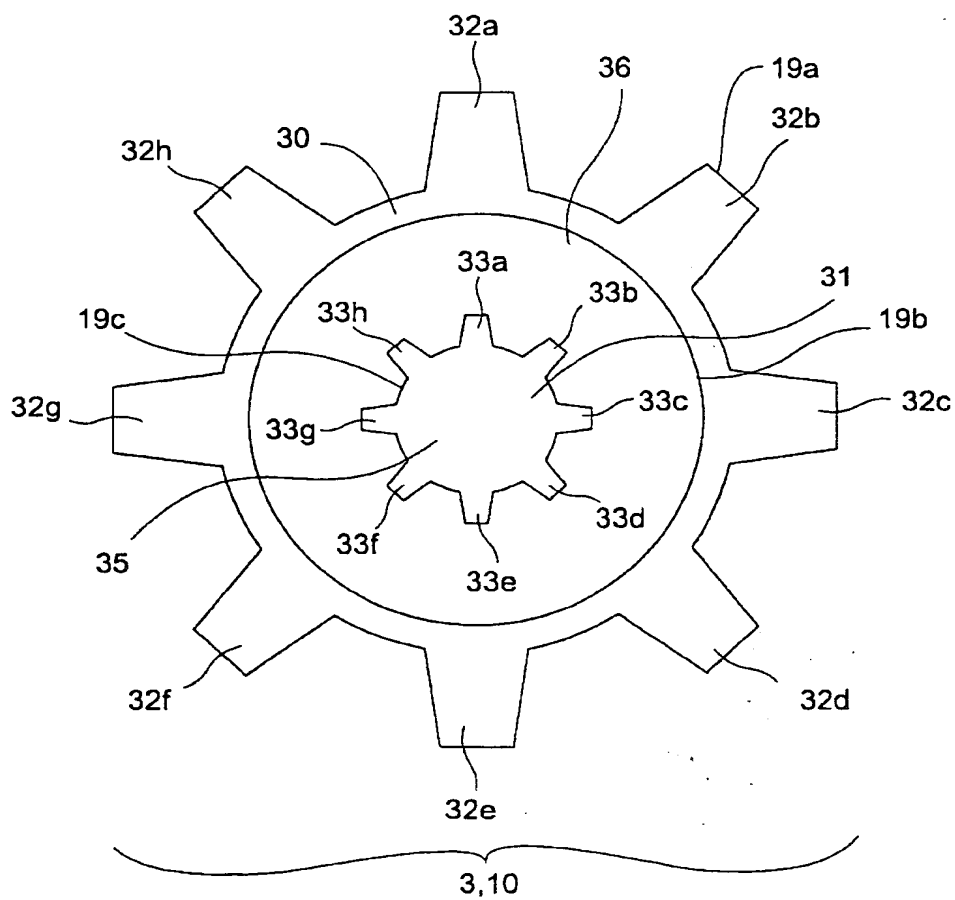


Fig. 10a

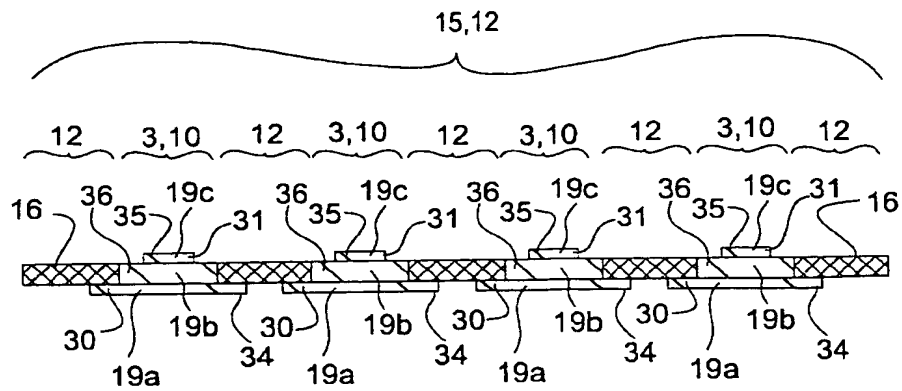


Fig. 11b

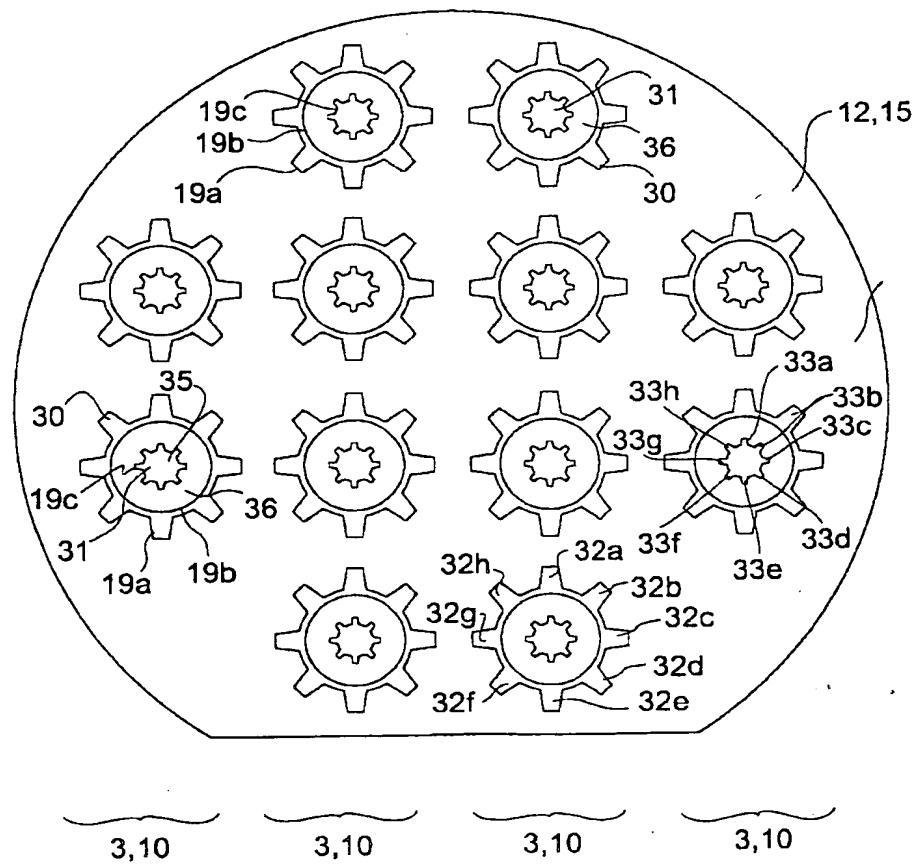


Fig. 11a

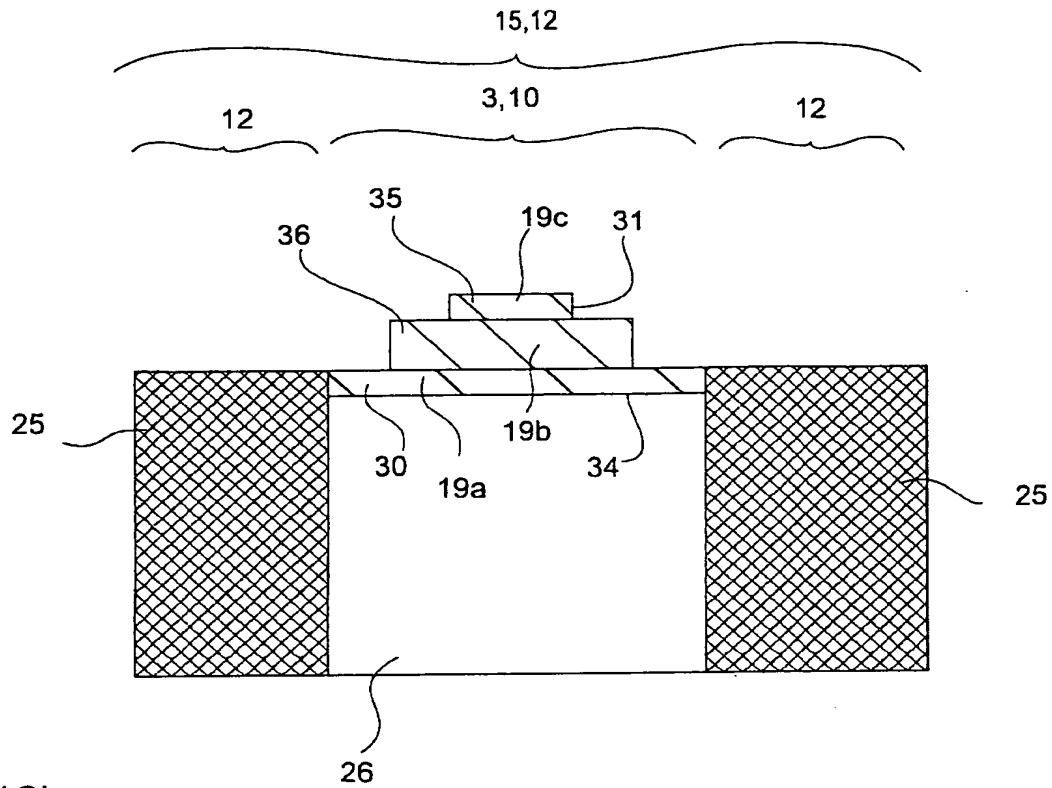


Fig. 12b

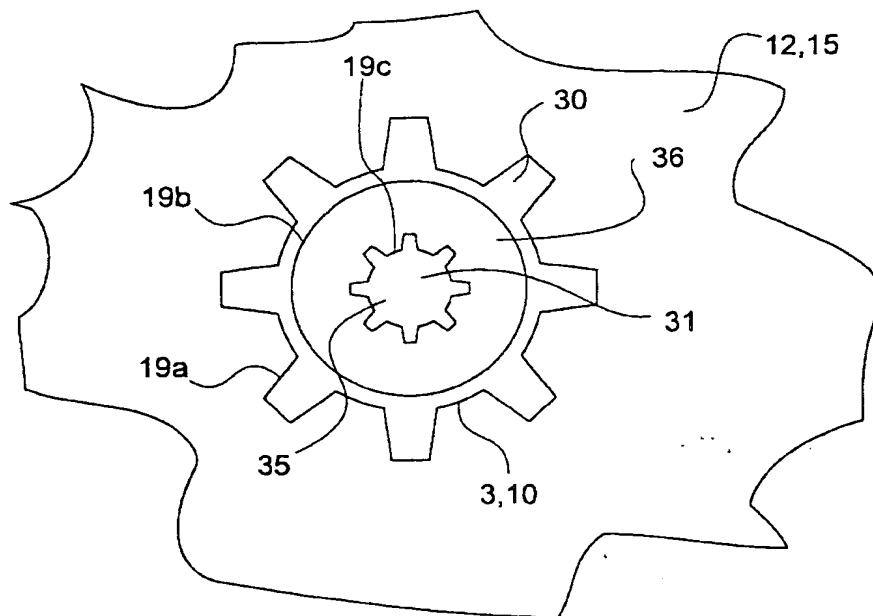


Fig. 12a

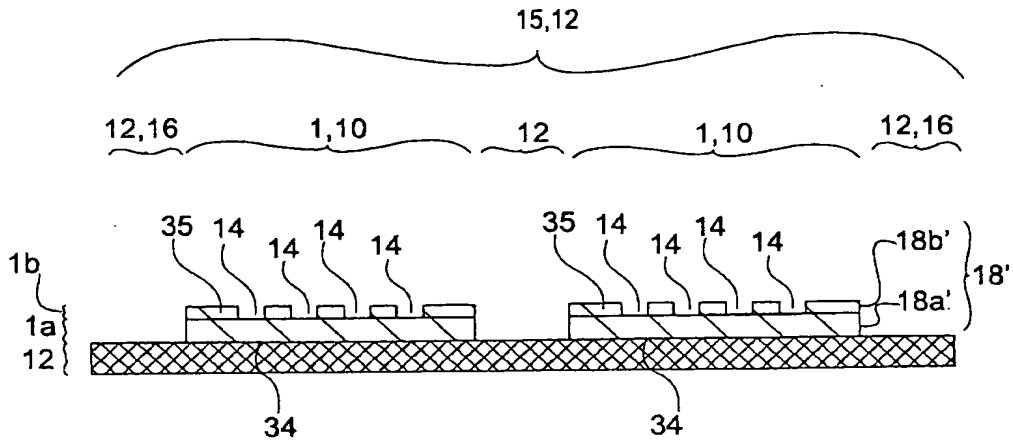


Fig. 13b

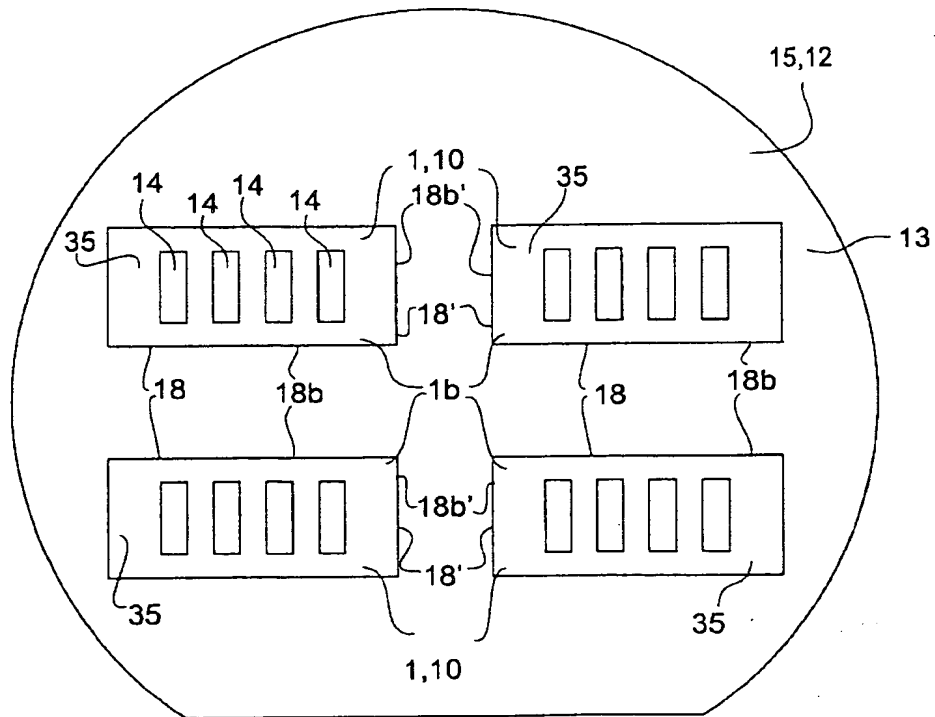


Fig. 13a

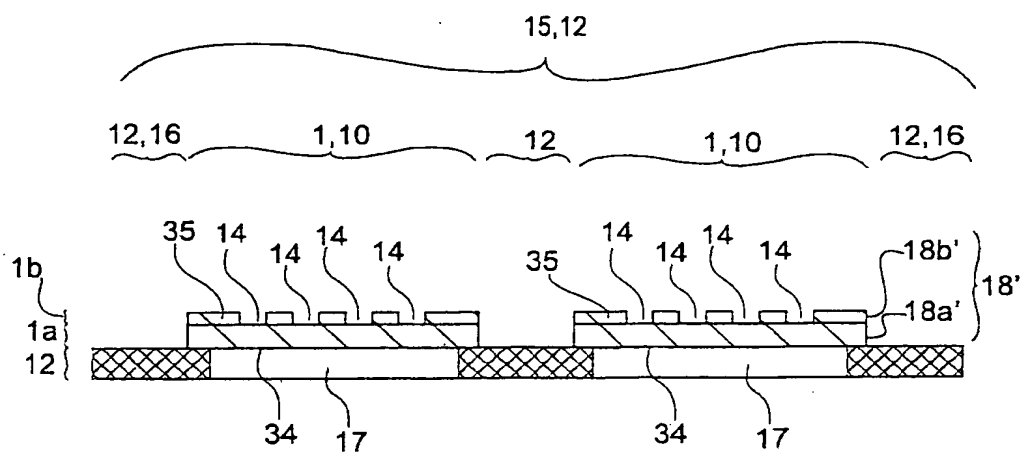


Fig. 14b

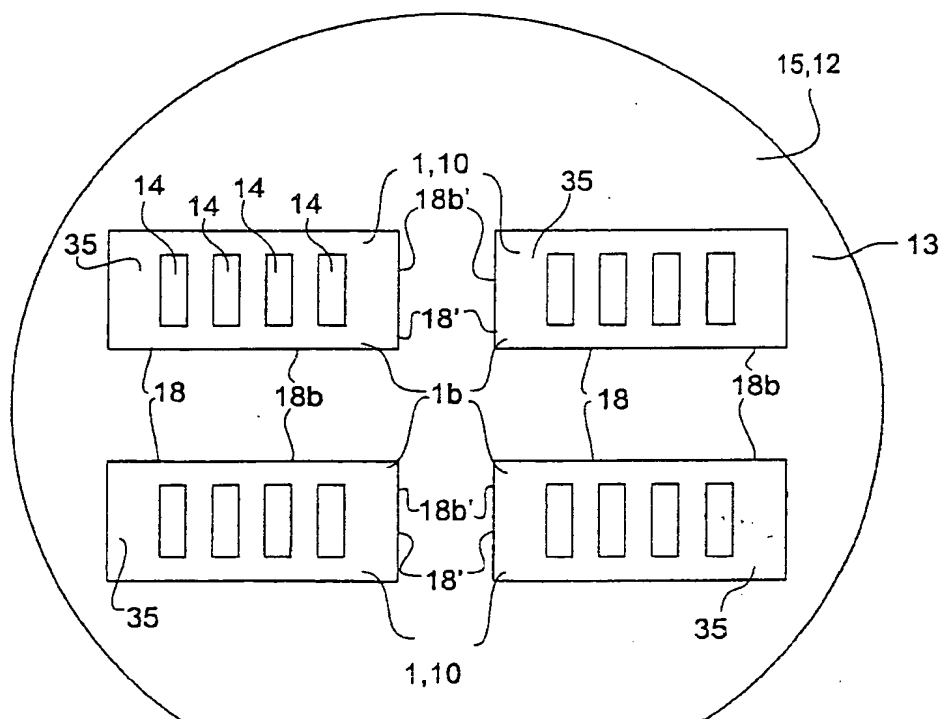


Fig. 14a

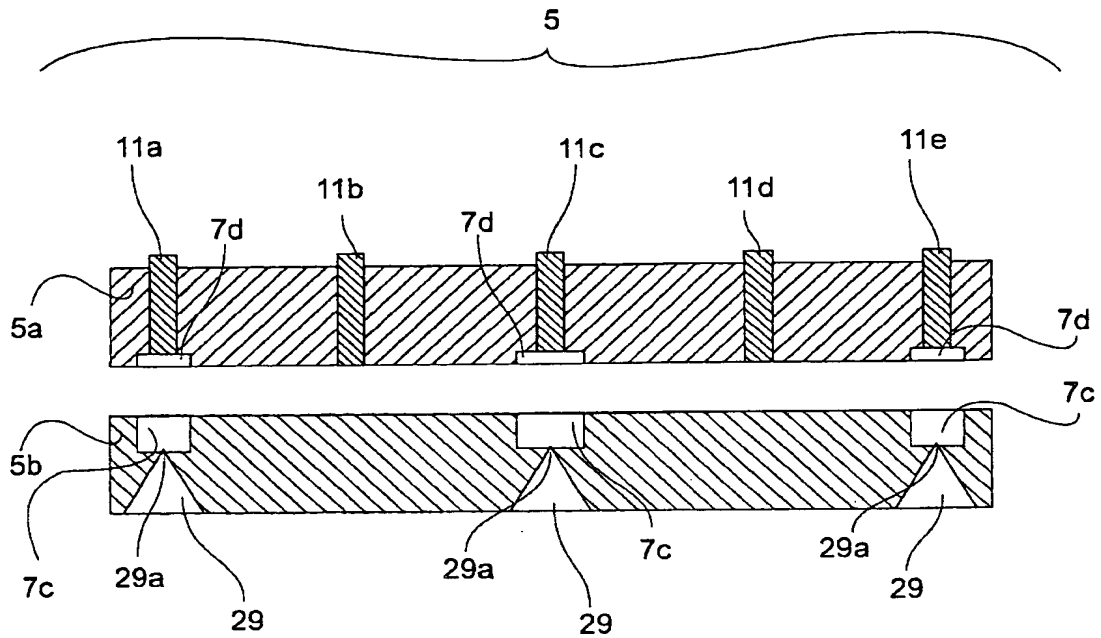


Fig. 15

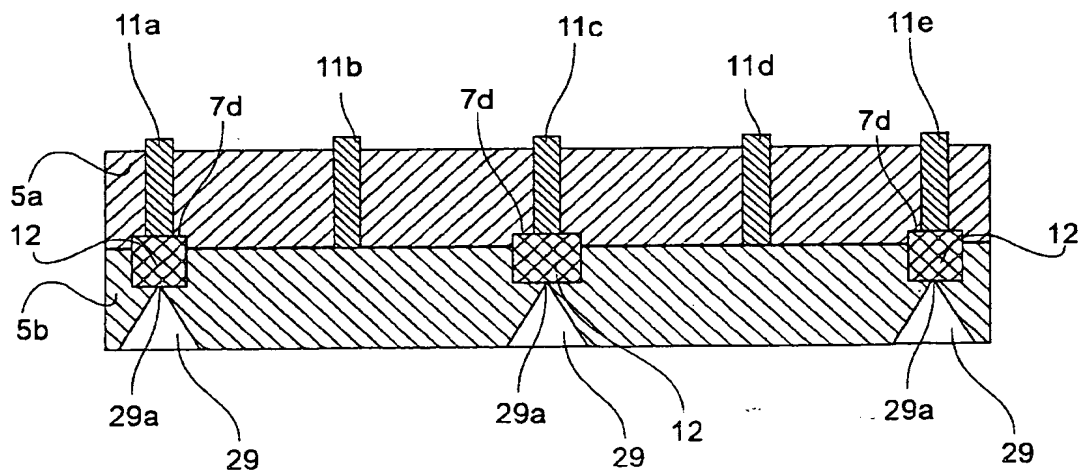


Fig. 16

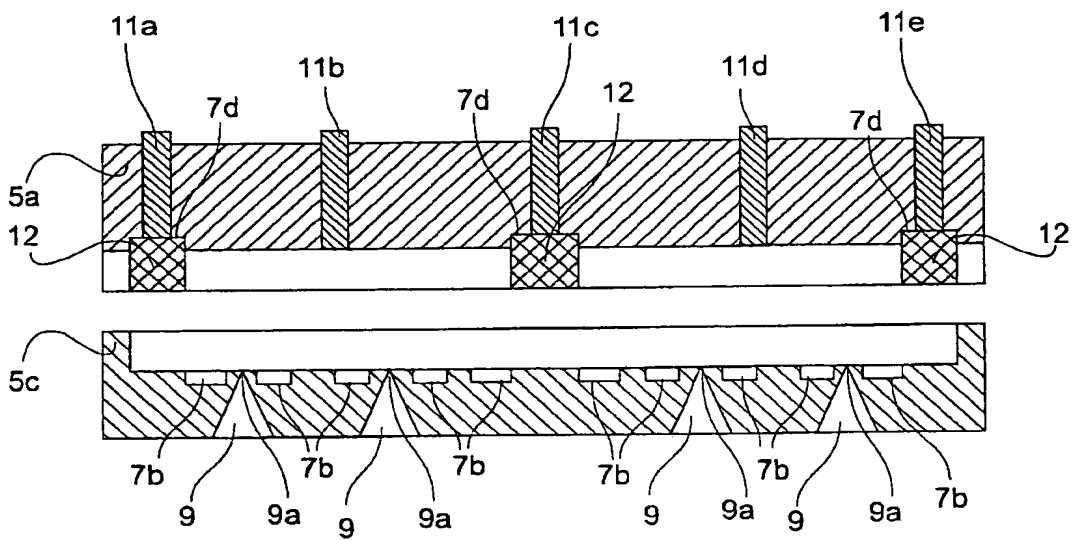


Fig. 17

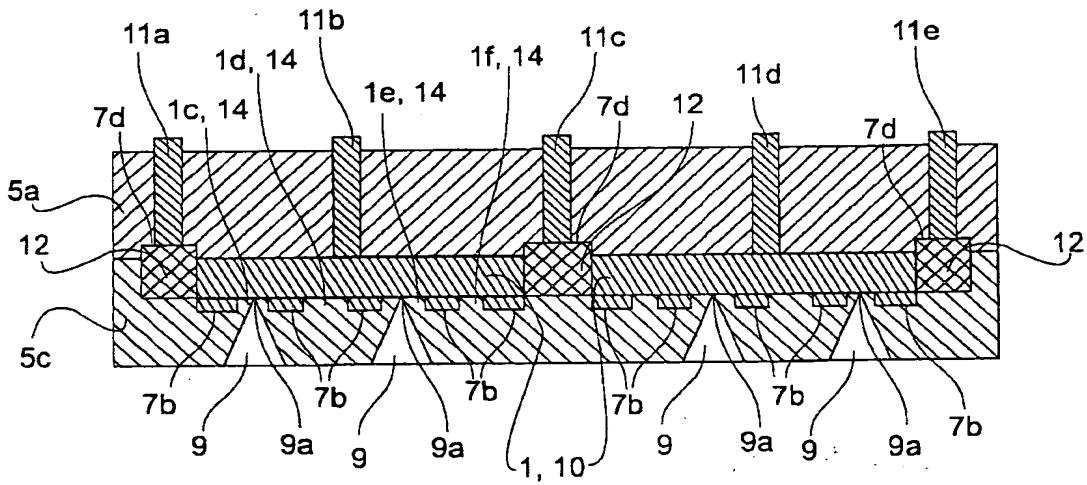


Fig. 18



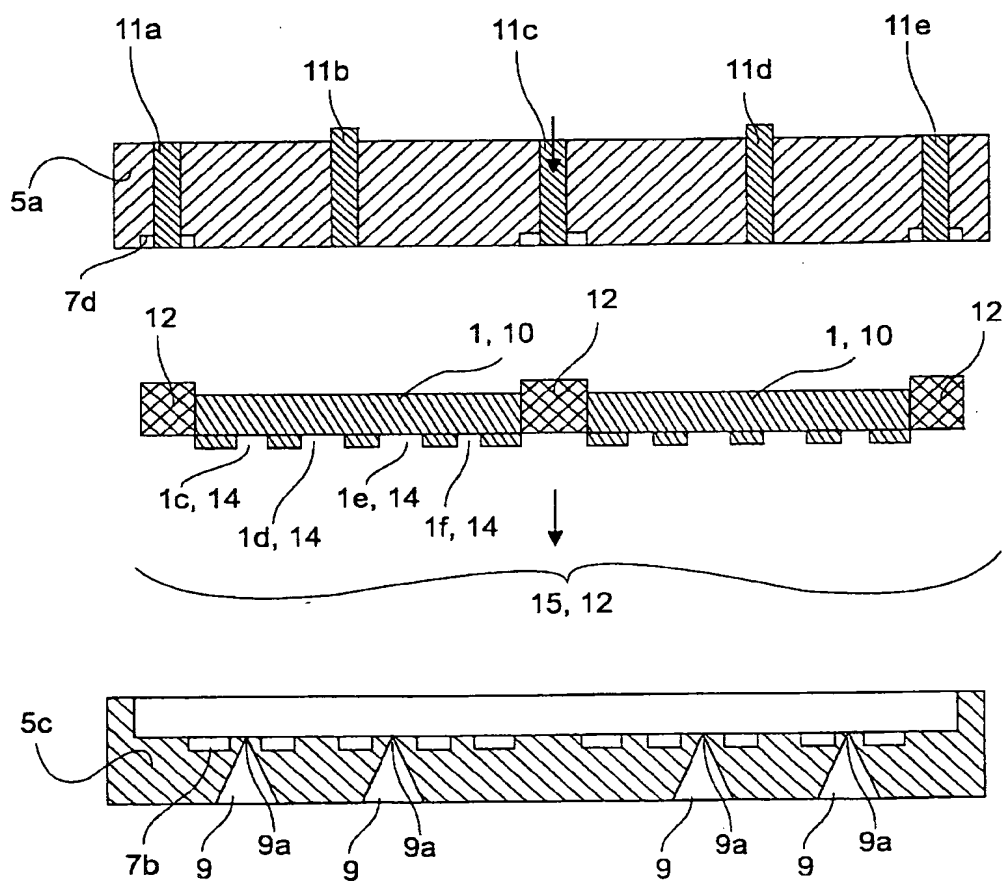


Fig. 19

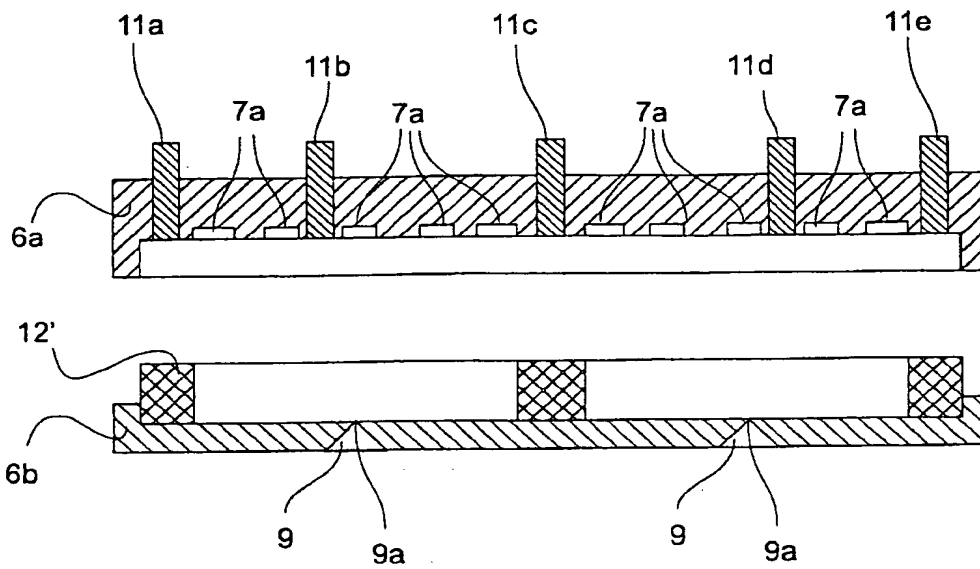


Fig. 20

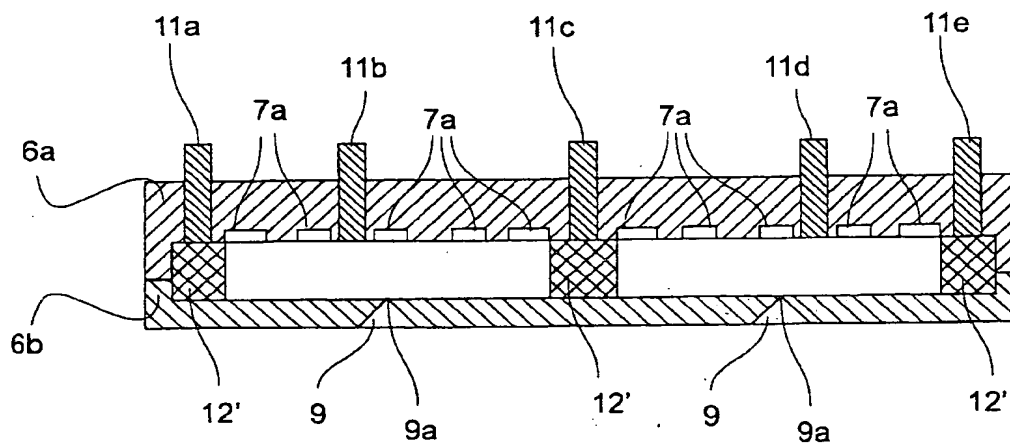


Fig. 21

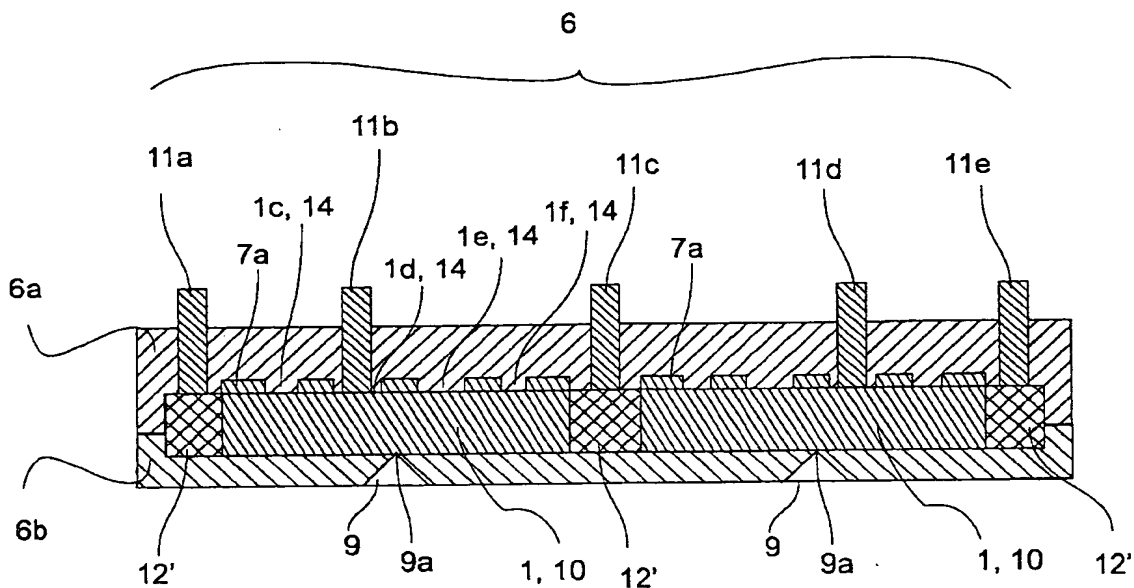


Fig 22

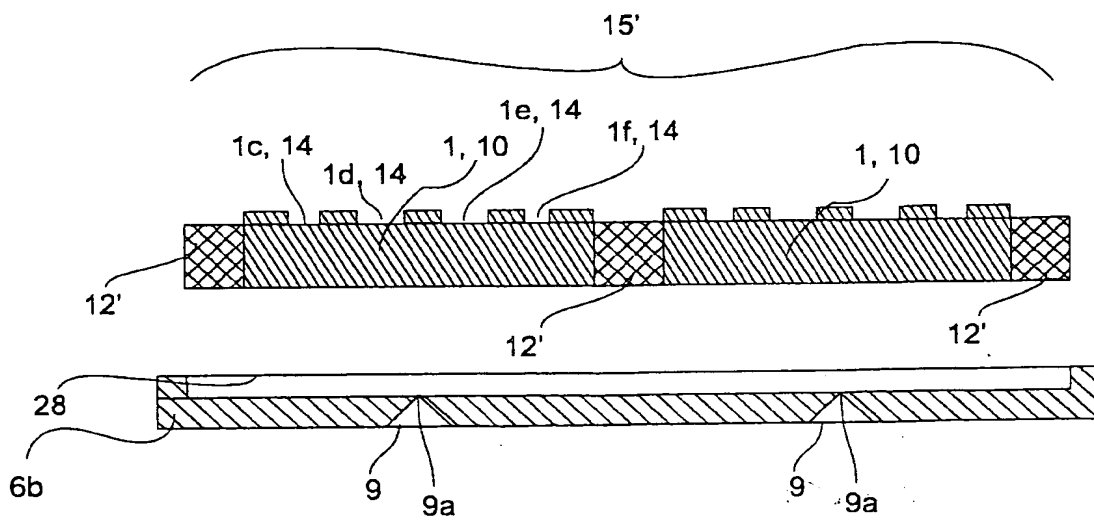
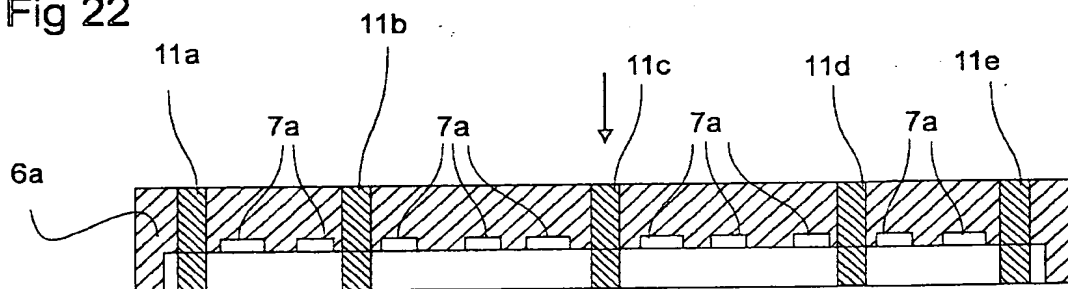


Fig 23